

Description

The 30P10 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO252-2L

General Features

$V_{DS} = -100V$ $I_D = -30 A$

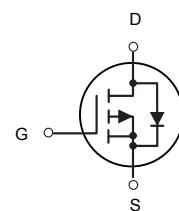
$R_{DS(ON)} < 95m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

Absolute Maximum Ratings ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_c=25^{\circ}\text{C}$	Continuous Drain Current, $V_{GS} @ -10V^1$	-30	A
$I_D@T_c=100^{\circ}\text{C}$	Continuous Drain Current, $V_{GS} @ -10V^1$	-15	A
I_{DM}	Pulsed Drain Current ²	-75	A
EAS	Single Pulse Avalanche Energy ³	157.2	mJ
I_{AS}	Avalanche Current	18.9	A
$P_D@T_c=25^{\circ}\text{C}$	Total Power Dissipation ⁴	54	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.3	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}$, $I_D=-10\text{A}$	---	78	95	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-8\text{A}$	---	86	110	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=-250\mu\text{A}$	-1.2	-1.7	-2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-100\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-50	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	±100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_D=-10\text{A}$	---	24	---	S
Q_g	Total Gate Charge	$V_{\text{DS}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_D=-20\text{A}$	---	44.5	---	nC
Q_{gs}	Gate-Source Charge		---	9.13	---	
Q_{gd}	Gate-Drain Charge		---	5.93	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_G=3.3\text{ }\Omega$, $I_D=-10\text{A}$	---	12	---	ns
T_r	Rise Time		---	27.4	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	79	---	
T_f	Fall Time		---	53.6	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	3029	---	pF
C_{oss}	Output Capacitance		---	129	---	
C_{rss}	Reverse Transfer Capacitance		---	76	---	
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-18	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$ I_F =-8\text{A}$, $dI/dt=-100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	38.7	---	nS
Q_{rr}	Reverse Recovery Charge		---	22.4	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.88\text{mH}$, $I^{AS}=-18.9\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

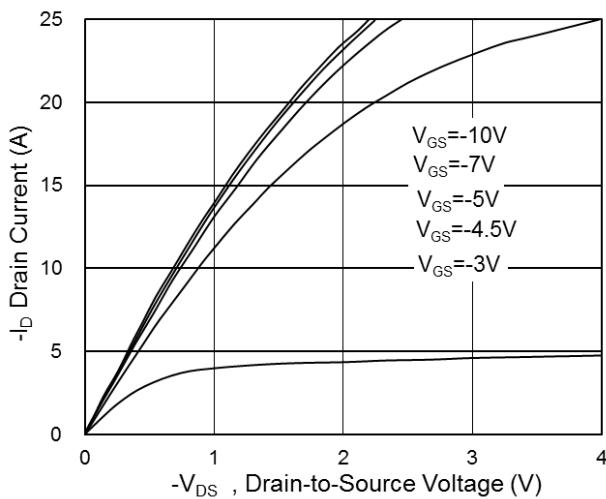


Fig.1 Typical Output Characteristics

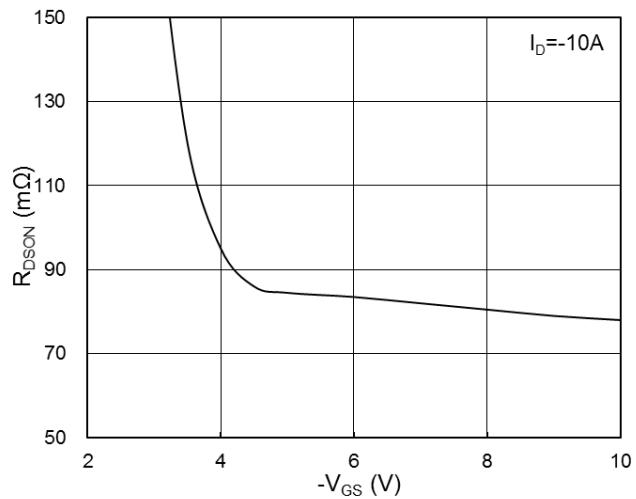


Fig.2 On-Resistance vs G-S Voltage

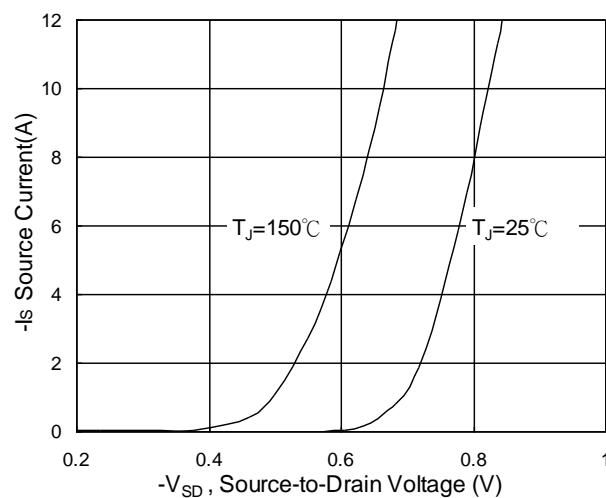


Fig.3 Typical S-D Diode Forward Voltage

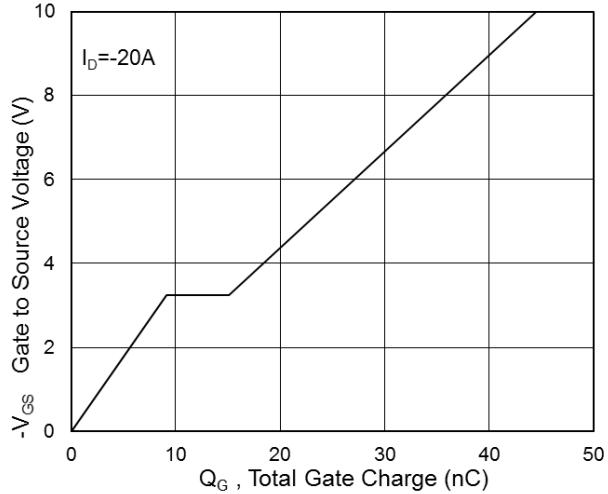


Fig.4 Gate-Charge Characteristics

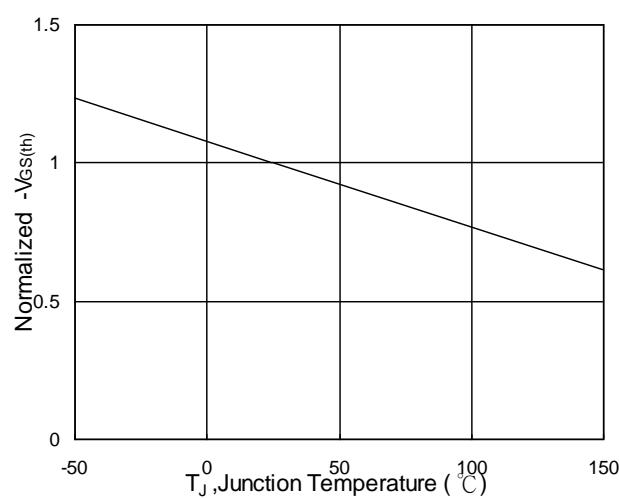


Fig.5 Normalized $V_{GS(th)}$ vs T_J

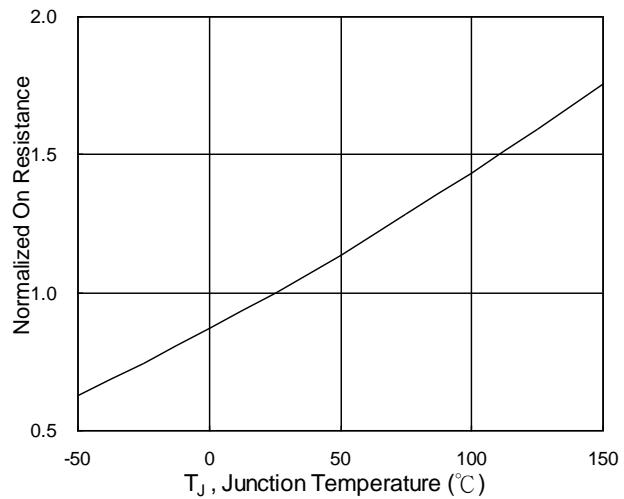


Fig.6 Normalized $R_{DS(on)}$ vs T_J

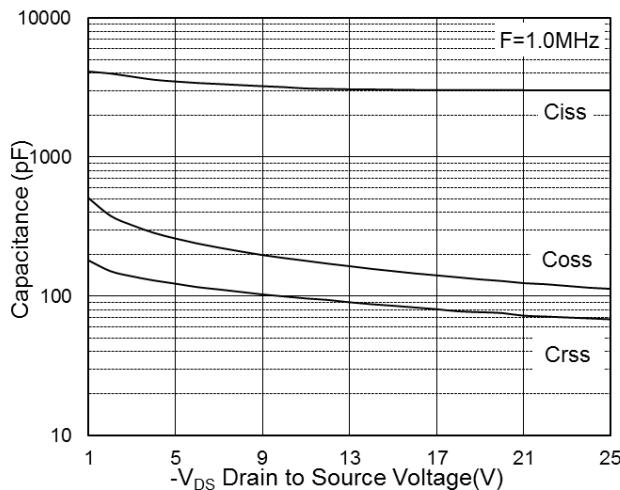


Fig.7 Capacitance

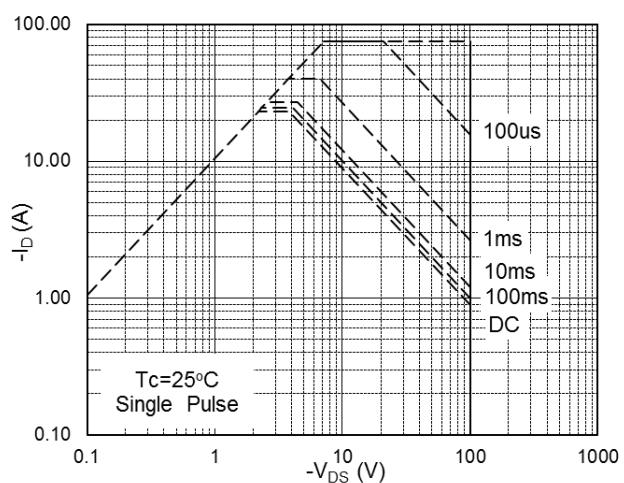


Fig.8 Safe Operating Area

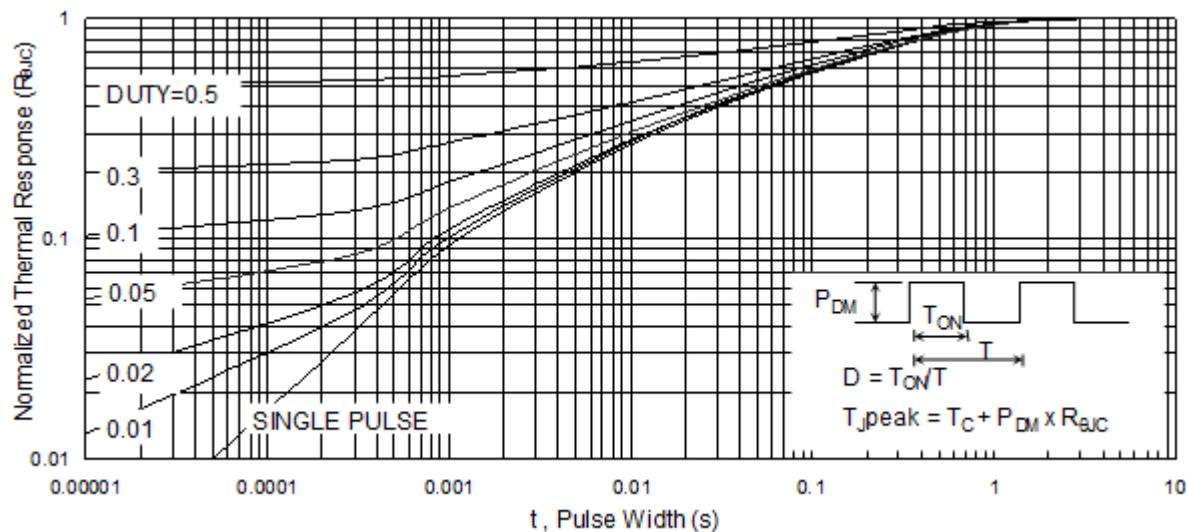


Fig.9 Normalized Maximum Transient Thermal Impedance

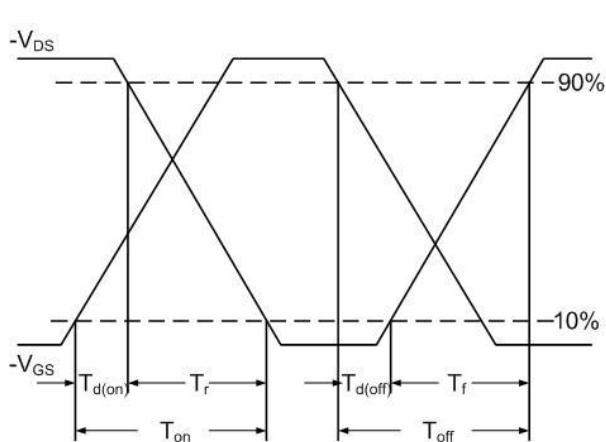


Fig.10 Switching Time Waveform

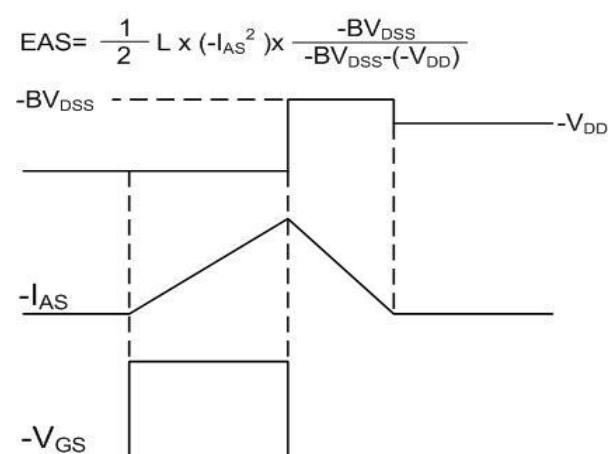
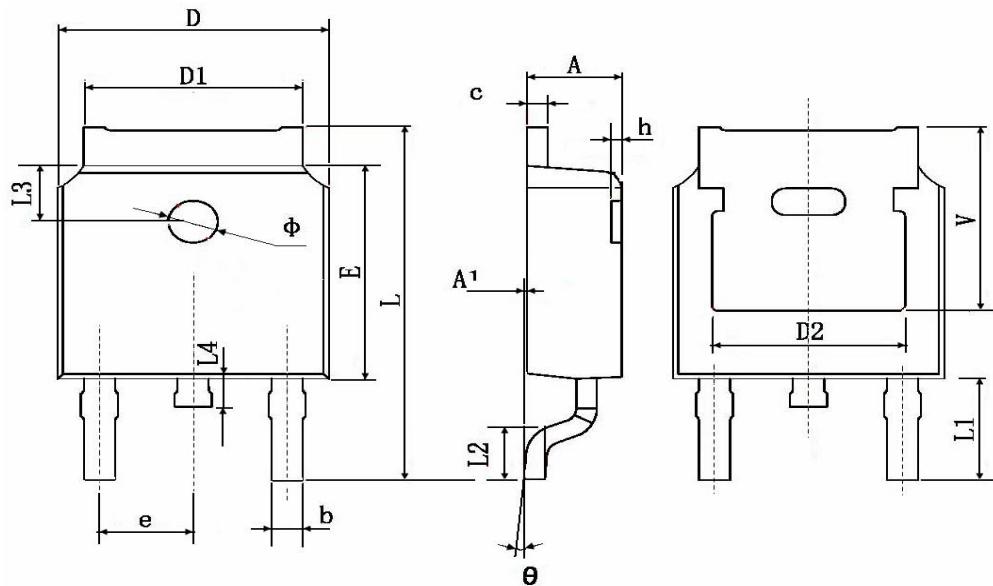


Fig.11 Unclamped Inductive Waveform

TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	